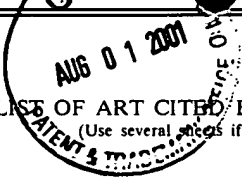
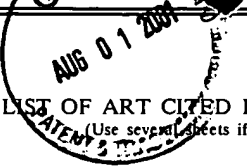
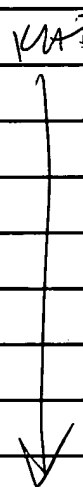


Form PTO-1449		 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			ATTY. DOCKET NO. M122-1694		SERIAL NO. 09/885,393	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT Micron Technology, Inc.			
					FILING DATE June 19, 2001		GROUP 1756	
U.S. PATENT DOCUMENTS								
*Examiner Initial	Class	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
KAD	AA	4,474,975	10/2/84	Clemons et al.	—	—		
	AB	5,962,581	10/5/99	Hayase et al.	—	—		
	AC	5,677,015	10/14/97	Hasegawa	—	—		
	AD	5,783,493	7/21/98	Yeh et al.	—	—		
	AE	5,807,660	9/15/98	Lin et al.	—	—		
	AF	4,833,096	5/23/89	Huang et al.	—	—		
	AG	5,405,489	4/11/95	Kim et al.	—	—		
	AH	5,470,772	11/28/95	Woo	—	—		
✓	AI	5,652,187	7/29/97	Kim et al.	—	—		
KAD	AJ	5,656,337	8/12/97	Park et al.	—	—		
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KAD	AK	0 942330	9/99	EPO	—	—		
KAD	AL	9 050993	2/97	Japan	—	—		
KAD	AM	406244172	9/94	Japan	—	—		
KAD	AN	593,727	10/47	GB	—	—		
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
KAD	AO	✓	Weidman, T. et al., "New Photodefinable Glass Etch Masks for Entirely Dry Photolithography: Plasma Deposited Organosilicon Hydride Polymers", Appl. Phys. Lett., Vol. 62, No. 4, Jan. 25, 1993, pp. 372-374.					
KAD	AP	✓	Weidman, T. et al., "All Dry Lithography: Applications of Plasma Polymerized Methylsilane as a Single Layer Resist and Silicon Dioxide Precursor", J. Photopolym. Sci. Technol., Vol. 8, No. 4, 1995, pp. 679-686.					
KAD	AQ	✓	Joubert, O. et al., "Application of Plasma Polymerized Methylsilane in an All Dry Resist Process for 193 and 248nm Lithography", Microelectronic Engineering 30 (1996), pp. 275-278.					
EXAMINER K. Duda				DATE CONSIDERED 8-5-02				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

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						FILING DATE June 19, 2001		GROUP 1756	
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	AA	4,805,683	2/21/89	Magdo et al.	—	—			
	AB	5,874,367	2/23/99	Dobson	—	—			
	AC	5,858,880	1/12/99	Dobson et al.	—	—			
	AD	5,219,613	6/15/93	Fabry et al.	—	—			
	AE	5,270,267	12/14/93	Ouellet	—	—			
	AF	5,541,445	7/30/96	Quellet	—	—			
	AG	6,022,404	2/8/00	Ettlinger et al.	—	—			
	AH	5,709,741	1/20/98	Akamatsu et al.	—	—			
	AI	4,648,904	3/10/87	DePasquale et al.	—	—			
	AJ	4,158,717	6/19/79	Nelson	—	—			
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	AK	5-263 255	10/93	Japan	—	—	X		
KMD	AL	0 464515	1/92	EPO	—	—			
KMD	AM	0 771886	5/97	EPO	—	—			
KMD	AN	63-157443	6/88	JP	—	—			
	AO	06 067019	3/94	JP (abstract)	—	—			
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)									
KMD	AP	✓	McClatchie, S. et al., "Low Dielectric Constant Flowfill" Technology for IMD Applications", Proceed. of 3d Internatl. Dielectrics for						
			ULSI Multilevel Interconnection Conf, Santa Clara, CA, Feb. 1997, pp. 34-40.						
KMD	AQ	✓	Beekman, K. et al., "Sub-Micron Gap Fill and In-Situ Planarisation Using Flowfill" Technology", ULSI Conf, Portland, OR,						
			Oct. 1995, pp. 1-7.						
	AR	✓	Kiermasz, A. et al., "Planarisation for Sub-Micron Devices Utilising a New Chemistry", DUMIC Conf., California, Feb. 1995, pp. 1-2.						
EXAMINER <u>K. Duda</u>				DATE CONSIDERED <u>8-5-02</u>					
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>									

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(KAD) V (KAD)	AA	5,667,015	9/16/97	Harestad et al.	/	/		
	AB	5,661,093	8/26/97	Ravi et al.	/	/		
	AC	5,536,857	7/16/96	Narula et al.	/	/		
	AD	4,695,859	9/22/87	Guha et al.	/	/		
	AE	5,061,509	10/29/91	Naito et al.	/	/		
	AF	4,600,671	7/15/86	Saitoh et al.	/	/		
	AG	5,753,320	5/19/98	Mikoshiba et al.	/	/		
	AH	5,356,515	10/18/94	Tahara et al.	/	/		
	AI	6,054,379	4/25/00	Yau et al.	/	/		
	AK	5,800,877	9/1/98	Maeda et al.	/	/		
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	AL 20029	US99	Search Report				/	
	AM 20030	US99	Search Report				/	
	AN							
	AO							
	AP							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
(KAD)	AQ	Bencher, C. et al., "Dielectric Antireflective Coatings for DUV Lithography", Solid State Technology, Mar. 1997, pp. 109-114.						
(KAD)	AR	Shibata, N., "Plasma-Chemical Vapor-Deposited Silicon Oxide/Silicon Oxynitride Double-Layer Antireflective Coating for Solar Cells", Jap. Journ. of Applied Physics, Vol. 30, No. 5, May 1991, pp. 997-1001.						
(KAD)	AS	McKenzie, D., et al., "New Technology for PACVD", Surface and Coatings Technology, Vol. 82, 1996, pp. 326-333.						
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Micron Technology, Inc.FILING DATE
June 19, 2001GROUP
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
KAD	AA	5,260,600	11/9/93	Harada	/	/	
	AB	4,992,306	2/12/91	Hochberg et al.	/	/	
	AC	4,702,936	10/27/87	Maeda et al.	/	/	
	AD	4,863,755	9/5/89	Hess et al.	/	/	
	AE	5,234,869	8/10/93	Mikata et al.	/	/	
	AF	5,302,366	4/12/94	Schuette et al.	/	/	
	AG	5,591,494	1/7/97	Sato et al.	/	/	
	AH	5,968,611	10/19/99	Kaloyeros et al.	/	/	
	AI	6,159,871	12/12/00	Loboda et al.	/	/	
	AJ	5,461,003	10/24/95	Havemann et al.	/	/	
	AK	6,124,641	9/26/00	Matsuura	/	/	
KAD	AL	5,554,567	9/10/96	Wang	/	/	

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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

KAD	AO	✓	Withmall, R. et al., "Matrix Reactions of Methylsilanes and Oxygen Atoms", Phys. Chem. 1988, pages 92, 594-602.
KAD	AP	✓	Joshi, A.M. et al., "Plasma Deposited Organosilicon Hydride Network Polymers as Versatile Resists for Entirely Dry Mid-Deep UV Photolithography", SPIE Vol. 1925, pages 709-720.
KAD	AQ	✓	Matsuura M. et al., "A Highly Reliable Self-planarizing Low-k Intermetal Dielectric for Sub-quarter Micron Interconnects", IEEE, pages 785-788.
KAD	AR	✓	Horie, O. et al., "Kinetics and Mechanism of the Reactions of O ^{(1)P} with SiH ₄ , CH ₃ SiH ₃ , (CH ₃) ₂ SiH ₂ , and (CH ₃) ₃ SiH", American Chemical Society 1991, pages 4393-4400.

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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1694SERIAL NO.
09/885,393

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U.S. PATENT DOCUMENTS

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UAD	AA	6,028,015	2/22/00	Wang et al.	—	—	
	AB	5,744,399	4/28/98	Rostoker et al.	—	—	
	AC	5,883,014	3/16/99	Chen et al.	—	—	
	AD	6,156,674	12/5/00	Li et al.	—	—	
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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

UAD	AO	✓	TEXT: Ralls, K. et al., "Introduction to Materials Science and Engineering", 1976 John Wiley & Sons, Inc., pp. 312-313.
UAD	AP	✓	Laxman, R. et al., "Synthesizing Low-K CVD Materials for Fab Use", Semiconductor Internatl., Nov. 2000, pp. 95-102 (printed from www.semiconductor-intl.com).
UAD	AQ	✓	Anonymous, "New Gas Helps Make Faster ICs", Machine Design, Vol. 71, Iss. 21, Nov. 4, 1999, p. 118.
UAD	AR	✓	IBM Technical Disclosure Bulletin, "Low-Temperature Deposition of SiO ₂ , Si ₃ N ₄ or SiO ₂ -Si ₃ N ₄ ", Volume Number 28, Issue Number 9, Page Number 4170.

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	AA	App. 09/146,842 (as filed and amended)	Yin et al.			9/98		
	AB	App. 09/146,843 (as filed and amended)	Li et al.			9/98		
	AC	App. 09/030,618 (as filed and amended)	Mohsner et al.			2/98		
	AD	App. 09/234,233 (as filed and amended)	Li et al.			1/99		
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KM	AP	ABSTRACT: Loboda, M. et al., "Using Trimethylsilane to Improve Safety, Throughput and Versatility in PECVD Processes", Electrochemical Society Meeting Abstract No. 358, 191 st Meeting, Montreal, Quebec, Vol. MA 97-1, 1997, page 454.						
KM	AQ	Julius Grant, "Hack's Chemical Dictionary", McGraw-Hill Book Company 1969, Fourth Edition, page 27.						
	AR							
EXAMINER <i>K. Dueda</i>				DATE CONSIDERED <i>8-5-02</i>				
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>								

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M122-1694		SERIAL NO. 09/885,393	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Richard Holscher et al.			
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KAD	AA 5,314,724	05/24/94	Tsukune et al.	427	489		
KAD	AB 5,376,591	12/27/94	Maeda et al.	437	238		
KAD	AC 5,817,549	10/06/98	Yamazaki et al.	438	166		
KAD	AD 6,072,227	06/06/00	Yau et al.	257	642		
KAD	AE 6,001, 741	12/14/99	Alers	438	706		
KAD	AF 5,786,039	07/28/98	Brouquet	427	578		
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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1694SERIAL NO.
09/885,393LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)APPLICANT
Richard Holscher et al.FILING DATE
June 19, 2001GROUP
1756

U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date if Applicable
KAD	AA	6,235,568	05/2001	Murthy et al.	438	231	
	AB	6,187,694	02/2001	Cheng et al.	438	947	
	AC	5,750,442	5/1998	Juengling	438	761	
	AD	6,114,255	9/2000	Juengling	438	763	
	AE	6,238,976	5/2001	Noble et al.	438	259	
	AF	6,008,121	12/1999	Yang et al.	438	637	
	AG	5,140,390	8/1992	Li et al.	357	23.7	
	AH	5,286,661	2/1994	de Fresart et al.	437	31	
	AI	6,184,151	2/2001	Adair et al.	438	743	
	AJ	6,225,217	5/2001	Usami et al.	438	637	
	AK	6,004,850	12/1999	Lucas et al.	438	301	
KAD	AL	6,140,677	10/2000	Gardner et al.	257	327	

FOREIGN PATENT DOCUMENTS

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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

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U.S. DEPARTMENT OF COMMERCE
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ATTY. DOCKET NO.
M122-1694

SERIAL NO.
09/885,393

APPLICANT
Richard Holscher et al.

FILING DATE
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LIST OF ART CITED BY APPLICANT
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U.S. PATENT DOCUMENTS

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KUD	AU 6,133,096	10/2000	Su et al.	438	264	
	AV 6,136,636	10/2000	Wu	438	231	
	AW 5,933,721	8/1999	Hause et al.	438	217	
	AX 5,981,368	11/1999	Gardner et al.	438	595	
	AY 6,159,804	12/2000	Gardner et al.	438	265	
	AZ 6,130,168	10/2000	Chu et al.	438	717	
	BA 6,235,591	5/2001	Balasubramanian et al.	438	275	
	BB 6,198,144	3/2001	Pan et al.	257	412	
	BC 5,801,399	9/1998	Hattori et al.	257	69	
	BD 5,994,730	11/1999	Shrivastava et al.	257	306	
	BE 6,040,619	3/2000	Wan g et al.	257	649	
KUD	BF 6,060,765	5/2000	Maeda	257	635	

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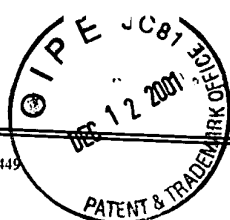
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U.S. PATENT DOCUMENTS

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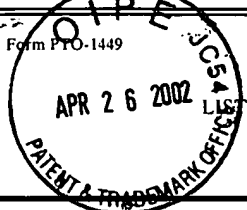
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KMD	AA	6,087,267	06/00	Dockrey et al.	438	719			
KMD	AB	5,543,654	08/96	Dennen	257	386			
KMD	AC	5,656,330	08/97	Niiyama et al.	427	255			
KMD	AD	5,872,035	02/99	Kim et al.	438	261			
KMD	AE	4,444,617	04/84	Whitcomb	156	643			
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	AK								
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